



EDFAS Lifetime Achievement Award

EDFAS Lifetime Achievement Award was established by the EDFAS Board of Directors in 2015 to recognize leaders in the EDFAS community who have devoted their time, knowledge, and abilities towards the advancement of the electronic device failure analysis industry.

Recipients of the Lifetime Achievement Award

2025

Dr. David Hung-I Su

Adjunct Professor

National Tsing Hua University

Citation: "For his work on the adoption of FIB and TEM techniques in volume manufacturing, his outstanding contribution to EDFAS, and his advocacy of Failure Analysis in Asia and North America."

2024

Dr. Ted Lundquist

Senior Manager

Zeiss Smt Pcs (retired)

Citation: "Ted Lundquist is remembered for his dedicated board service, impactful contributions to conferences, and generosity in mentoring engineers. His groundbreaking work in FIB and lock-in thermography has revolutionized microelectronic device failure analysis."

2023

Mr. David Albert

Failure Analysis Engineer (retired)

IMB Corp

Citation: *“In recognition of dedication and leadership in the sustained development of the Nano-Probing fault isolation technique over 42 years and being a patient teacher and loyal custodian in EDFAS.”*

2022

Dr. Michael Bruce

Consultant

Citation: *“For his lifetime contributions to the advancement of backside failure analysis techniques and the development and adoption of Soft Defect Localization, which has become a mainstay tool across the Semiconductor Industry.”*

2021

Dr. William E. Vanderlinde, FASM

Director

Advanced Computing Systems Laboratory for Physical Sciences

Citation: *“For his contributions to the advancement of failure analysis for over 30 years, including research in electron microscopy and the conception and leadership of the Circuit Analysis Tools program at IARPA which led to significant advancements in semiconductor failure analysis.”*

2020

Dr. Philippe Perdu, FASM

President

ANADEF / CNES

Citation: *“For his career long technique development, wholehearted service to microelectronic failure analysis community, tireless mentoring for students and young engineers, and relentless pursuit of tool adaptation for microelectronics application including integrated circuits, microsystems, system on chip and 3D integrated packaging.”*

2019

Dr. Thomas Moore, FASM

President

Waviks Inc.

Citation: *“For his significant contributions in FIB lift-out and SAM phase inversion technologies which reshaped the failure analysis industry and for his wholehearted commitment to education and mentoring in the failure analysis community.”*

2018

Dr. Edward I. Cole Jr., FASM
Senior Fellow
Sandia National Laboratories

Citation: *“For his development and implementation of microelectronics defect localization tools to enhance advancement of integrated circuits, and his commitment to education and mentoring in the failure analysis community.”*

2017

Mr. Richard J. Ross
Consultant/Lecturer
Semiconductor Devices

Citation: *“For continued strong dedication to ASMA and EDFAS, to the field of electronic device failure analysis, and specifically to the discipline of failure analysis engineering management.”*